

Study of Fast Neutron Interactions in Silicon by Timepix detectors

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INTRODUCTION

Detectors, neutron source, data evaluation techique, ...





Timepix Detectors

Timepix detectors

- Hybrid pixel detectors
- Developed at CERN
- 256 x 256 pixel
- Pixel pitch: 55µm
- Silicon sensor layer flip-chip bump bonded to the ASIC

Timepix:

- Thickness: 1mm
- Depletion voltage: 400V
- Framebased readout (Acq.time 100µs, dead time ~ 11ms)
- Measurement of either energy or time (used in the time mode: resolution 20.6 ns)
- Threshold set to 4.5 keV

□ Timepix 3:

- Thickness: 300µm
- Depletion voltage: 90V
- Data driven readout (Maximal count rate 40 Mpix/s)
- Measurement of energy and time, simultaneously (time resolution 1.56 ns)

LANSCE

 Threshold set to 5 keV (down to ~2 keV possible)



Los Alamos Neutron Science CEnter (LANSCE)



15L 30L

4

LANSCE

LANSCE: Detector setup and neutron energy spectrum









Investigated detectors $d_{IP} = 20.8 \text{ m}$

STEF

Pattern recognition – definition of different cluster types





the LANSCE neutron beam.

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TIMEPIX

Results and discussion by means of radiation damage



TIMEPIX: Cluster shapes (detector responses) as a function of neutron kinetic energy



The ToF technique^{*)} was used to assign the detector responses to the corresponding neutron energies (track by track).





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- Dots, small blobs (LETE)
- Displacement damage

- Heavy tracks and heavy blobs (HETE)
- Single Event Upsets (SEU) and Multiple Bit Upsets (MBU), permanent damage

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TIMEPIX3

First look and preliminary results ...



Timepix3 CERN chip board

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TIMEPIX3: Cluster shapes (detector responses) as a function of neutron kinetic energies



- Same behaviour as for Timepix
- Better time resolution leads to better selection of neutron kinetic energies



TIMEPIX3: Examples of energy spectra for selected neutron energy intervals



LANSCE

Neutron elastic scattering



Energy transfer to the silicon nucleus:

$$T_{Si,max} = \frac{4M_{Si}m_n}{(M_{Si} + m_n)^2} T_n = 0.133 \cdot T_n$$

 \rightarrow Energy goes partly into displacement (NIEL) and ionization



Neutron elastic scattering



LANSCE

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Neutron scattering: Losses by ionization vs losses due to displacement

*) The formulae for the calculation can be found in: C. Leroy and P.-G. Rancoita, Rep. Prog. Phys. 70 (2007) 493-625

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SUMMARY AND CONCLUSION

- The response in the form of tracks of a hybrid active pixel detector with silicon sensor layer for different neutron energies was studied by using the ToF technique
 - Different track shapes indicate the different interactions and energy depositions in the sensor layer
 - The detector responses were tried to be interpreted in the context of radiation damage
- A newly developed type of Timepix detectors was tested in the measurement for the first time allowing the simultaneous measurement of energy and time
 - Study the non-ionizing vs. ionizing energy losses (especially for the lower energy region)
 - Deeper insight of the processes leading to the different cluster shapes
 - Understand the nature of SEU and MBU (by coincidence measurement with failures of electronic devices)

Thank you for your attention!



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